# **Specification of Thermoelectric Module**

TEC1-12735S

### **Description**

The 127 couples, 55 mm × 55 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

#### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

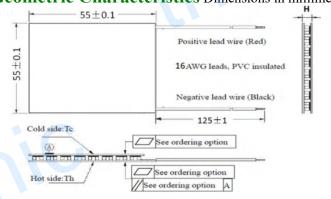
## Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### **Performance Specification Sheet**

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	16	17.2	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max(</sub> amps)	30	30	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	300.5	328.4	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	0.41	0.50	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

#### Geometric Characteristics Dimensions in millimeters



# **Ordering Option**

Suffix	Thickness	Flatness/	Lead wire length(mm)			
	(mm)	Parallelism (mm)	Standard/Optional length			
TF	0:4.0±0.1	0:0.1/0.1	125±1/Specify			
TF	1:4.0±0.05	1:0.05/0.05	125±1/Specify			
Fig. TF00: Thickness 4.0 ± 0.1 (mm) and Flatness 0.1 / 0.1 (mm)						

#### Eg. 1F00: Thickness $4.0 \pm 0.1$ (mm) and Flatness 0.1 / 0.1 (mm)

## **Manufacturing Options**

A. Solder:	]	B. Sealant:

1. T100: BiSn (Tmelt=138°C) 1. NS: No sealing (Standard)

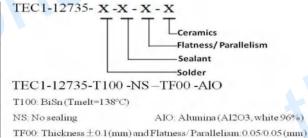
2. T200: CuAgSn (Tmelt =  $217^{\circ}$ C) 2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C) 3. EPS: Epoxy sealant

C. Ceramics: D. Ceramics Surface Options:

1. Blank ceramics (not metalized) 1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

# Naming for the Module

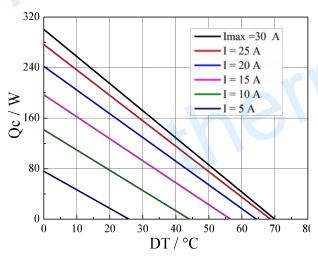


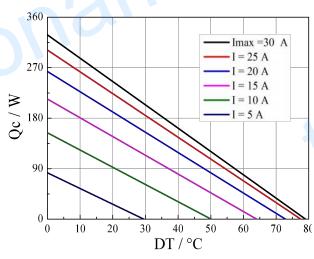
# **Specification of Thermoelectric Module**

### **TEC1-12735S**

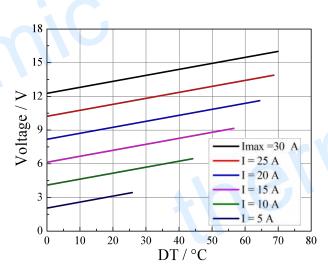
## Performance Curves at Th=27 °C

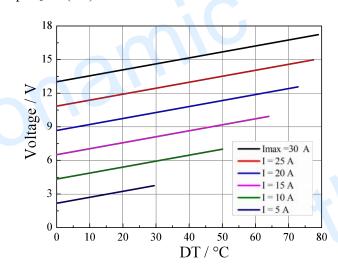
### Performance Curves at Th=50 °C



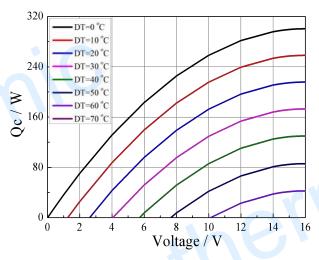


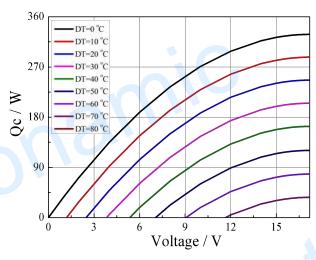
Standard Performance Graph Qc= f(DT)





Standard Performance Graph  $V = f(\Delta T)$ 





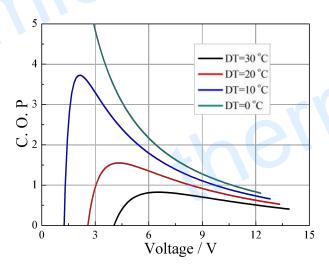
Standard Performance Graph Qc = f(V)

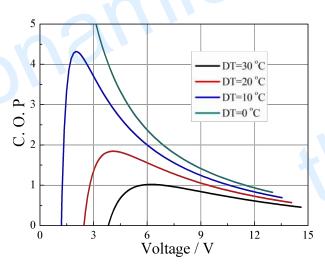
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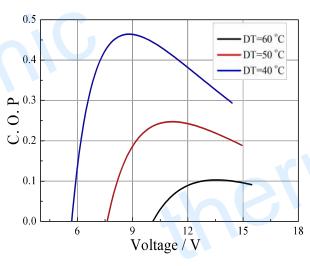
### Performance Curves at Th=27 °C

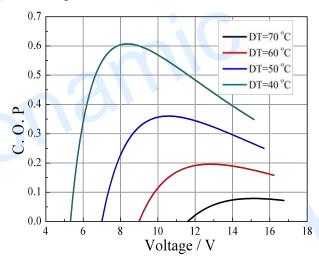
### Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

## **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100 °C
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC